## Surge and Over-Voltage Protection Switch for VBUS <br> FPF2280

## Description

The FPF2280 features a low- $\mathrm{R}_{\mathrm{ON}}$ internal FET and an operating range of $2.5 \mathrm{~V}_{\mathrm{DC}}$ to $5.5 \mathrm{~V}_{\mathrm{DC}}$ (absolute maximum of $29 \mathrm{~V}_{\mathrm{DC}}$ ). An internal clamp is capable of shunting surge voltages $>100 \mathrm{~V}$, protecting downstream components and enhancing system robustness. The FPF2280 features over-voltage protection that powers down the internal FET if the input voltage exceeds the OVP threshold. The OVP threshold is adjustable with optional external resistors. Over-temperature protection also powers down the device at $130^{\circ} \mathrm{C}$ (typical). Exceptionally low off-state current ( $<1 \mu \mathrm{~A}$ maximum) facilitates compliance with standby power requirements.

The FPF2280 is available in a fully "green" compliant $1.3 \mathrm{~mm} \times$ 1.8 mm Wafer-Level Chip-Scale Package (WLCSP) with backside laminate.

## Features

- Surge Protection
- IEC 61000-4-5: > 100 V
- Over-Voltage Protection (OVP)
- Over-Temperature Protection (OTP)
- ESD Protection
- Human Body Model (HBM): > 3.5 kV
- Charged Device Model (CDM): > 2 kV
- IEC 61000-4-2 Air Discharge: > 15 kV
- IEC 61000-4-2 Contact Discharge: > 8 kV
- This is a $\mathrm{Pb}-$ Free Device


## Typical Applications

- Mobile Handsets and Tablets
- Portable Media Players
- MP3 Players


WLCSP12 1.288×1.828×0.586 CASE 567QX

## MARKING DIAGRAM



| HC | $=$ Specific Device Code |
| :--- | :--- |
| ZZ | $=$ Assembly Lot Code |
| Y | $=$ Year |
| W | $=$ Work Week |
| A | $=$ Assembly Location |

ORDERING INFORMATION

| Part Number | Top Marking | Operating Temperature Range | Package | Shipping $^{\dagger}$ |
| :---: | :---: | :---: | :---: | :---: |
| FPF2280BUCX-F130 | HC | $-40^{\circ} \mathrm{C}$ to $+105^{\circ} \mathrm{C}$ | WLCSP12 (Pb-Free) | $3000 /$ Tape \& Reel |

$\dagger$ For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

## FPF2280

## Block Diagram



Figure 1. Functional Block Diagram

## Pin Configuration



Figure 2. Pin Configuration

PIN DEFINITIONS

| Name | Bump | Type |  | Description |  |
| :---: | :---: | :---: | :--- | :--- | :--- |
| IN | B3, C2, C3 | Input/Supply | Switch Input and Device Supply |  |  |
| OUT | A2, A3, B2 | Output | Switch Output to Load | 1 | VIN < VIN_min or VIN $\geq$ VovLO |
| \#ACOK | B1 | Output <br> (Open Drain) | Power Good | Voltage Stable |  |
| \#EN | A1 | Input | Device Enable ( Active LOW) |  |  |
| OVLO | C1 | Input | Over-Voltage Lockout Adjustment Pin |  |  |
| GND | A4, B4, C4 | Supply | Device Ground |  |  |

## Over-Voltage Lockout (OVLO) Calculation

OVLO can be set externally and override default OVP. By connecting an external resistor-driver to the OVLO pin. Equation (1) can produce the desired trip voltage and resistor values.

$$
\begin{equation*}
\mathrm{V}_{\text {IN_OVLO }}=\mathrm{V}_{\text {OVLO_TH }} \times[1+\mathrm{R} 1 / R 2] \tag{eq.1}
\end{equation*}
$$

Recommended minimum R1 $=1 \mathrm{M} \Omega$

## On-The-Go (OTG) Functionality

During OTG operation, the FPF2280 is initially disabled and the power FET's bulk diode is forward biased. The bulk
diode represents $\sim 0.7 \mathrm{~V}$ drop across the device, which remains until the V_IN voltage increases past 2.5 V , when the device is fully enabled. While the device is disabled and the body diode is forward biased, the max DC current through the diode is 1.8 A . This current is limited by the thermal performance of the device $(0.7 \mathrm{~V} \times 1.8 \mathrm{~A}=1.36 \mathrm{~W})$. This current should be transient; the \#EN pin must be pulled LOW to ensure the device fully enables. The transient should not exceed the RC time constant of the C_IN and C_OUT capacitors. At the system level, over-voltage and current protection should be provided outside the FPF2280.

ABSOLUTE MAXIMUM RATINGS

| Symbol | Parameter |  | Min. | Max. | Unit |
| :---: | :---: | :---: | :---: | :---: | :---: |
| $\mathrm{V}_{\text {IN }}$ | V_IN to GND \& V_IN to V_OUT = GND or Float |  | -0.3 | 29.0 | V |
| $\mathrm{V}_{\text {OUT }}$ | V_OUT to GND |  | -0.3 | $\mathrm{V}_{\mathrm{IN}}+0.3$ | V |
| $\mathrm{V}_{\text {OVLO }}$ | OVLO to GND |  | -0.3 | 24.0 | V |
| $\mathrm{V}_{\text {\#EN_ACOK }}$ | Maximum DC Voltage Allowed on \#EN or ACOK Pin |  |  | 6 | V |
| 1 N | Switch I/O Current (Continuous) |  |  | 4.5 | A |
| $t_{\text {PD }}$ | Total Power Dissipation at $\mathrm{T}_{\mathrm{A}}=25^{\circ} \mathrm{C}$ |  |  | 1.48 | W |
| $\mathrm{T}_{\text {STG }}$ | Storage Temperature Range |  | -65 | 150 | ${ }^{\circ} \mathrm{C}$ |
| $\mathrm{T}_{J}$ | Maximum Junction Temperature |  |  | 150 | ${ }^{\circ} \mathrm{C}$ |
| $\mathrm{T}_{\mathrm{L}}$ | Lead Temperature (Soldering, 10 Seconds) |  |  | 260 | ${ }^{\circ} \mathrm{C}$ |
| ӨJA | Thermal Resistance, Junction-to-Ambient ${ }^{(1)}$ (1-in. ${ }^{2}$ Pad of 2-oz. Copper) |  |  | 84.1 | ${ }^{\circ} \mathrm{C} / \mathrm{W}$ |
| ESD | IEC 61000-4-2 System ESD | Air Gap | 15.0 |  | kV |
|  |  | Contact | 8.0 |  |  |
|  | Human Body Model, ANSI/ESDA/JEDEC JS-001-2012 | All Pins | 3.5 |  |  |
|  | Charged Device Model, JESD22-C101 | All Pins | 2.0 |  |  |
| Surge | IEC 61000-4-5, Surge Protection | $\mathrm{V}_{\text {IN }}$ | 100 |  | V |

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Measured using 2S2P JEDEC std. PCB

RECOMMENDED OPERATING CONDITIONS

| Symbol | Parameter | Min. | Max. | Unit |
| :---: | :--- | :---: | :---: | :---: |
| $\mathrm{V}_{\mathbb{I}}$ | Supply Voltage | 2.5 | 20.0 | V |
| $\mathrm{~T}_{\mathrm{A}}$ | Operating Temperature | -40 | 105 | ${ }^{\circ} \mathrm{C}$ |

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

## ELECTRICAL CHARACTERISTICS

( $\mathrm{T}_{\mathrm{A}}=-40^{\circ} \mathrm{C}$ to $105^{\circ} \mathrm{C}$ unless otherwise indicated. Typical values are $\mathrm{V}_{\mathbb{I N}}=5.0 \mathrm{~V}, \mathrm{I}_{\mathbb{N}} \leq 3 \mathrm{~A}, \mathrm{C}_{I N}=0.1 \mu \mathrm{~F}$ and $\mathrm{T}_{\mathrm{A}}=25^{\circ} \mathrm{C}$.)

| Symbol | Parameter | Conditions | Min. | Typ. | Max. | Unit |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| VIN_CLAMP | Input Clamping Voltage | $\mathrm{I}_{\mathrm{N}}=10 \mathrm{~mA}$ |  | 35 |  | V |
| $\mathrm{I}_{\mathrm{Q}}$ | Input Quiescent Current | $\mathrm{V}_{\mathrm{IN}}=5 \mathrm{~V}$, \#EN $=0 \mathrm{~V}$ |  | 58 | 100 | $\mu \mathrm{A}$ |
| $\mathrm{I}_{\mathrm{N}, \mathrm{Q}}$ | OVLO Supply Current | $\mathrm{V}_{\text {OVLO }}=3 \mathrm{~V}, \mathrm{~V}_{\text {IN }}=5 \mathrm{~V}, \mathrm{~V}_{\text {OUT }}=0 \mathrm{~V}$ |  | 63 | 100 | $\mu \mathrm{A}$ |
| $\mathrm{V}_{\text {IN_OVLO }}$ | Internal Over-Voltage Trip Level | $\mathrm{V}_{\text {IN }}$ Rising, OVLO = GND | 6.6 | 6.8 | 7.0 | V |
|  |  | $\mathrm{V}_{\text {IN }}$ Falling | 6.2 |  |  | V |
| VovLo_TH | OVLO Set Threshold | $\mathrm{V}_{\text {IN }}=2.5 \mathrm{~V}$ to $\mathrm{V}_{\text {OVLO }}$ | 1.12 | 1.20 | 1.24 | V |
| VovLo_RNG | Adjustable OVLO Threshold Range | $\mathrm{V}_{\text {IN }}=2.5 \mathrm{~V}$ to $\mathrm{V}_{\text {OVLO }}$ | 4 |  | 20 | V |
| VovLo_select | External OVLO Select Threshold |  |  | 0.30 | 0.28 | V |
| $\mathrm{R}_{\mathrm{ON}}$ | Resistance from $\mathrm{V}_{\text {IN }}$ to $\mathrm{V}_{\text {OUT }}$ | $\mathrm{V}_{\text {IN }}=5 \mathrm{~V}, \mathrm{l}_{\text {OUT }}=1 \mathrm{~A}, \mathrm{~T}_{\mathrm{A}}=25^{\circ} \mathrm{C}$ |  | 30 | 39 | $\mathrm{m} \Omega$ |
| Cout | OUT Load Capacitance ${ }^{(2)}$ | $\mathrm{V}_{\mathrm{IN}}=5 \mathrm{~V}$ |  |  | 1000 | $\mu \mathrm{F}$ |
| lolvo | OVLO Input Leakage Current | VovLO = VovLo_TH | -100 |  | 100 | nA |
| $\mathrm{T}_{\text {SDN }}$ | Thermal Shutdown ${ }^{(2)}$ |  |  | 130 |  | ${ }^{\circ} \mathrm{C}$ |
| T ${ }_{\text {SDN_HYS }}$ | Thermal Shutdown Hysteresis ${ }^{(2)}$ |  |  | 20 |  | ${ }^{\circ} \mathrm{C}$ |

Digital Signals

| V OL | \#ACOK Output Low Voltage | $\mathrm{V}_{\mathrm{I} / \mathrm{O}}=3.3 \mathrm{~V}, \mathrm{I}_{\text {SINK }}=1 \mathrm{~mA}$ |  | 0.4 | V |
| :---: | :---: | :---: | :---: | :---: | :---: |
| VIH_\#EN | Enable HIGH Voltage | $\mathrm{V}_{\text {IN }}=2.5 \mathrm{~V}$ to $\mathrm{V}_{\text {OVLO }}$ | 1.2 |  | V |
| VIL_\#EN | Enable LOW Voltage | $\mathrm{V}_{\text {IN }}=2.5 \mathrm{~V}$ to $\mathrm{V}_{\text {OVLO }}$ |  | 0.5 | V |
| IACOK_LEAK | \#ACOK Leakage Current | $\mathrm{V}_{1 / \mathrm{O}}=3.3 \mathrm{~V}$, \#ACOK Deasserted, \#EN $=0 \mathrm{~V}$ | -0.5 | 0.5 | $\mu \mathrm{A}$ |
| \#EN_Leak | \#EN Leakage Current | $\mathrm{V}_{\text {IN }}=5.0 \mathrm{~V}, \mathrm{~V}_{\text {OUT }}=$ Float | -1.0 | 1.0 | $\mu \mathrm{A}$ |

Timing Characteristics

| $t_{\text {DEB }}$ | Debounce Time | Time from 2.5 $\mathrm{V}<\mathrm{V}_{\text {IN }}<\mathrm{V}_{\text {IN_ovLO }}$ to $\mathrm{V}_{\text {OUT }}=$ $0.1 \times \mathrm{V}_{\mathrm{IN}}$ | 15 | ms |
| :---: | :---: | :---: | :---: | :---: |
| ${ }_{\text {tstart }}$ | Soft-Start Time | Time from $\mathrm{V}_{\mathrm{IN}}=\mathrm{V}_{\mathrm{IN} \text { min }}$ to $0.2 \times$ \#ACOK, $\mathrm{V}_{\text {IO }}=1.8 \mathrm{~V}$ with $10 \mathrm{k} \Omega$ Pull-up Resistor | 30 | ms |
| ton | Switch Turn-On Time | $\mathrm{V}_{\text {IN }}=5 \mathrm{~V}, \mathrm{R}_{\mathrm{L}}=100 \Omega, \mathrm{~V}_{\text {OUT }}$ from $0.1 \times \mathrm{V}_{\text {IN }}$ to $0.9 \times \mathrm{V}_{\text {IN }}, \mathrm{C}_{\text {LOAD }}=100 \mu \mathrm{~F}$ | 2 | ms |
| toff | Switch Turn-Off Time ${ }^{(2)}$ | $\begin{aligned} & R_{L}=100 \Omega, C_{L}=0 \mu \mathrm{~F}, \mathrm{~V}_{\text {IN }}>\mathrm{V}_{\text {OVLO }} \text { to } \\ & \mathrm{V}_{\text {OUT }}=0.8 \times \mathrm{V}_{\text {IN }} \end{aligned}$ | 125 | ns |

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.
2. Guaranteed by characterization and design.

## FPF2280

## Timing Diagrams



Figure 3. Timing for Power Up and Normal Operation


Figure 4. Timing for OVLO Trip

PRODUCT-SPECIFIC PACKAGE DIMENSIONS

| $\mathbf{D}$ | $\mathbf{E}$ | $\mathbf{X}$ | $\mathbf{Y}$ |
| :---: | :---: | :---: | :---: |
| $1288 \mu \mathrm{~m} \pm 30 \mu \mathrm{~m}$ | $1828 \mu \mathrm{~m} \pm 30 \mu \mathrm{~m}$ | $314 \mu \mathrm{~m} \pm 18 \mu \mathrm{~m}$ | $244 \mu \mathrm{~m} \pm 18 \mu \mathrm{~m}$ |

## WLCSP12 1.288x1.828x0.586

CASE 567QX
ISSUE O
DATE 31 OCT 2016


SIDE VIEWS


BOTTOM VIEW

NOTES:
A. NO JEDEC REGISTRATION APPLIES.
B. DIMENSIONS ARE IN MILLIMETERS.
C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 2009.
D. DATUM C IS DEFINED BY THE SPHERICAL CROWNS OF THE BALLS.

PACKAGE NOMINAL HEIGHT IS 586 MICRONS $\pm 39$ MICRONS (547-625 MICRONS).
F. FOR DIMENSIONS D, E, X, AND Y SEE PRODUCT DATASHEET.

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